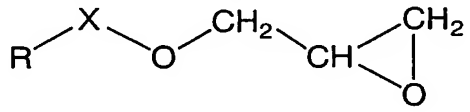
ABSTRACT

The invention provides a thermosetting resin composition comprising components (A) and (B), wherein the sum of components (A) and (B) is 90% by weight or more based on the composition; an adhesive film obtained from the composition; and a laminate obtained by laminating the film and an adherent and thermally curing the resultant. Component (A) is an amino acid or imidazoles, and component (B) is an epoxy group-containing ethylene copolymer obtained by polymerizing (b_1) and (b_2), wherein (b_1) is ethylene or propylene, and (b_2) is a monomer represented by formula (1):



(1)

, wherein R represents a hydrocarbon group of a carbon number of 2-18 having a double bond, wherein at least one of hydrogen atoms of the hydrocarbon group may be substituted with a halogen atom, a hydroxyl group or a carboxyl group, and X represents a single bond or a carbonyl group).